

## Summary

Xilinx® Alveo™ U200 and U250 Data Center accelerator cards are PCI Express® Gen3 x16 compliant cards designed to accelerate compute-intensive applications such as machine learning, data analytics, and video processing. A deployment shell enables the card to be configured from onboard memory through PCI Express.

## Alveo U200 and U250 Product Details

Table 1: Alveo U200 and U250 Accelerator Card Product Details

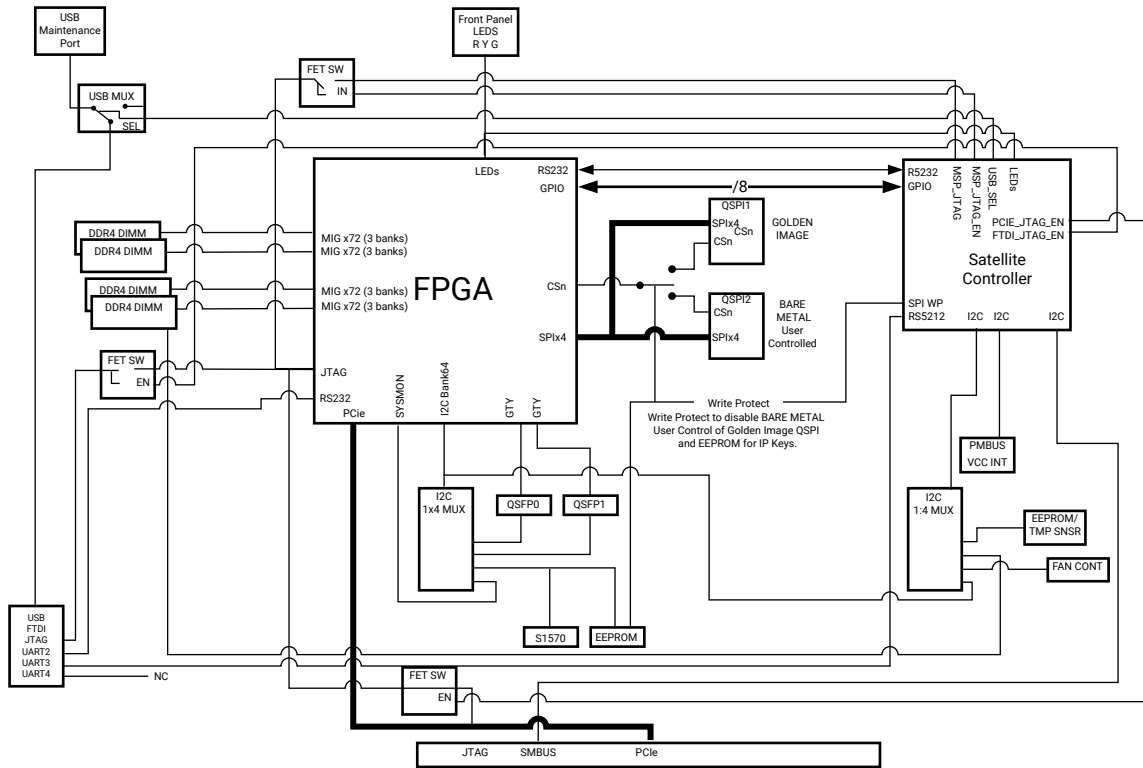
Specification	Active Cooling Version	Passive Cooling Version
Product SKU	<ul style="list-style-type: none"> <li>A-U200-A64G-PQ-G</li> <li>A-U250-A64G-PQ-G</li> </ul>	<ul style="list-style-type: none"> <li>A-U200-P64G-PQ-G</li> <li>A-U250-P64G-PQ-G</li> </ul>
Total electrical card load <sup>1</sup>	225W	225W
Thermal cooling solution	Active	Passive
Weight	1122g	1066g
Form factor	U200 and U250 cards fully comply with the double-slot PCIe form factor.	U200 and U250 cards fully comply with the double-slot PCIe form factor.

**Notes:**

- The 225W PCIe CEM card can take 65W from the standard connector 12V supply and an additional 150W from the AUX connector 12V supply. The 3.3V supply from the standard connector is not used on this card. The CEM card requires that a 150W PCIe AUX power cable be connected to the card.

The following figure shows the components within an Alveo U200 or U250 accelerator card.

Figure 1: U200 and U250 Block Diagram



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## Card Specifications

### Dimensions

The card is compliant with the PCIe CEM rev.3.0 Specification as a dual-slot, standard height card. The card with the passive cooling enclosure is three-quarter length, and the card with the active cooling enclosure is full length.

Table 2: Card Dimensions

Parameter	Dimension
Height	4.381 inch (111.28 mm) maximum
PCB thickness (+/- 0.1 3 mm (0.005 inch))	0.062 inch (1.57 mm)
<b>Active cooling enclosure installed</b>	
Assembly length	11.4 inch (29 cm)
Assembly thickness	1.52 inch (3.86 cm)
<b>Passive cooling enclosure installed</b>	
Assembly length	9.2 inch (23.4 cm)
Assembly thickness	1.44 inch (3.66 cm)

## PCIe Connector/Data Rates

Table 3: PCI Express 16-Lane Data Transfer Rate Performance

PCI Express Generation	Performance
Gen 1	2.5 GigaTransfers per second (GT/s)
Gen 2	5.0 GT/s
Gen 3	8.0 GT/s

## DDR4 Specifications

Four 288-pin DDR4 DIMM sockets are populated with single rank DIMMs capable of operating at data rates up to 2400 MegaTransfers per second (MT/s).

Table 4: DDR4 Interfaces

Parameter	Description
Manufacturer	Micron
Part Number	MTA18ASF2G72PZ-2G3B1
Description	16 GB 288-pin DDR4 RDIMM
	Configuration: 2Gb x 72
	Single rank
	Supports ECC error detection and correction
	Supports 2400 MT/s

## Network Interfaces

Both Alveo U200 and U250 accelerator cards host two 100G interfaces, each comprised of a 4-lane QSFP28 connector, which accepts up to 5W modules. QSFP connectors are not supported in the current version of the deployment shell. Each connector is housed within a single QSFP cage assembly.

## USB Maintenance Port

The Alveo U200 and U250 accelerator cards include a covered micro-USB maintenance port at the I/O bracket.

## Validated Servers

The Alveo U200 and U250 accelerator cards have been validated for interoperability by Xilinx in the following servers.

Table 5: Validated Servers

Manufacturer	Model/Platform
DELL	PowerEdge R730
DELL	PowerEdge R740

Table 5: Validated Servers (cont'd)

Manufacturer	Model/Platform
HPE	ProLiant DL380 G10
SuperMicro	SYS-4028GR-TR
SuperMicro	SYS-4029GP-TRT
SuperMicro	SYS-7049GP-TRT

## Operating System Compatibility

The following operating systems are supported:

- CentOS 7.4/7.5
- RHEL 7.4/7.5
- Ubuntu 16.04.4

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## FPGA Resource Information

At the heart of the Xilinx Alveo U200 and U250 accelerator cards are custom-built UltraScale+ FPGAs that run optimally (and exclusively) on Alveo. The Alveo U200 card features the XCU200 FPGA and the Alveo U250 card features the XCU250 FPGA. Both XCU200 and XCU250 FPGAs use Xilinx stacked silicon interconnect (SSI) technology to deliver breakthrough FPGA capacity, bandwidth, and power efficiency. This technology allows for increased density by combining multiple super logic regions (SLRs). The XCU200 comprises three SLRs and the XCU250 comprises four SLRs.

The deployment shell that handles device bring-up and configuration over PCIe is contained within the static region of the FPGA. The remaining dynamic region is available for application developers to implement custom accelerators.

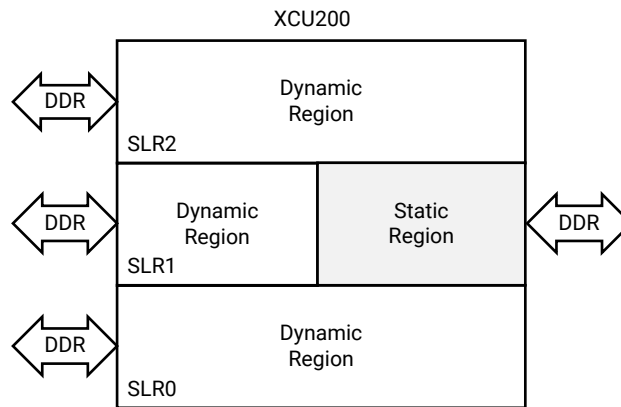
To access instructions on how to assign resources or kernels to the different SLRs in the device, refer to the "SLR Assignments for Kernels" appendix of the *SDAccel Environment User Guide* ([UG1023](#)).

## Dynamic Regions

The resources in the dynamic region are available for creating custom accelerators. The following figures and tables show the amount and location of resources available. For more information on the various resources and their capabilities, see the [Xilinx UltraScale+ documentation](#).

The following figure shows the static and dynamic regions of the XCU200 device.

Figure 2: Floorplan of the XCU200 Device



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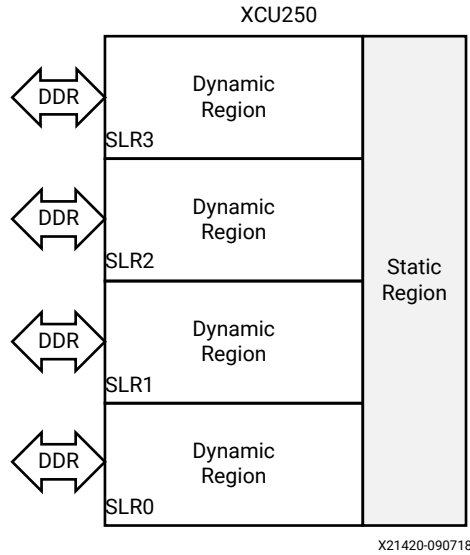
The following table lists available resources in the XCU200 device after the static region is programmed with the development shell.

Table 6: U200 Dynamic Region Resources

Resource	Total	SLR0	SLR1	SLR2
Look-Up Tables (LUTs) (K)	892	365	162	365
Registers (K)	1831	746	339	746
36 Kb Block RAMs	1766	695	376	695
288 Kb UltraRAMs	800	320	160	320
DSP Slices	5867	2275	1317	2275

The following figure shows the static and dynamic regions of the XCU250 device.

Figure 3: Floorplan of the XCU250 Device



The following table lists available resources in the XCU250 device after the static region is programmed with the development shell.

Table 7: U250 Dynamic Region Resources

Resource	Total	SLR0	SLR1	SLR2	SLR3
Look-Up Tables (LUTs) (K)	1341	338	332	332	339
Registers (K)	2749	693	680	680	696
36 Kb Block RAMs	2000	500	500	500	500
288 Kb UltraRAMs	1280	320	320	320	320
DSP Slices	11508	2877	2877	2877	2877

## Thermal Specification

### Ambient Conditions

The ambient conditions are detailed in the following sections.

### Operating and Storage Temperature Conditions

Table 8: Operating and Storage Temperatures and Humidity Conditions

Specification	Condition
Operating temperature	0°C to 45°C
Storage temperature	-40°C to 75°C
Operating humidity	8% to 85%

Table 8: Operating and Storage Temperatures and Humidity Conditions (cont'd)

Specification	Condition
Storage humidity	5% to 90%

## Standard Compliance Details

The Alveo U200 and U250 accelerator cards are compliant with ASHRAE classes A1, A2, and A3. The maximum operating altitude is 1200m above sea level.

Table 9: Standard Compliance Details

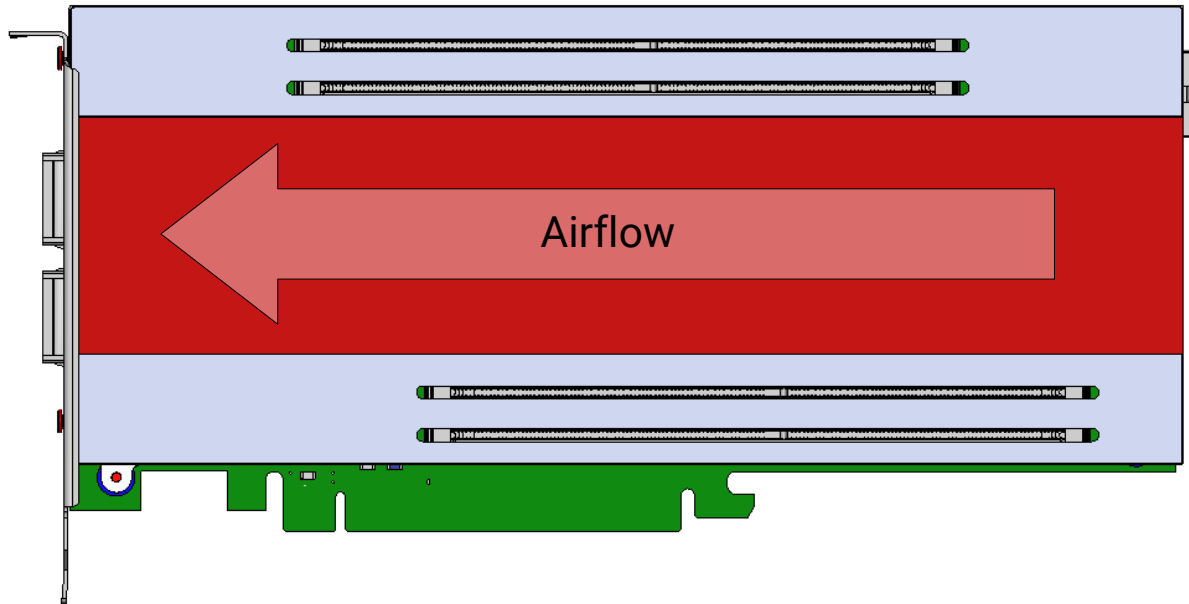
Standard		Operation		Recommended	
		Temperature (C)	Humidity Ratio	Temperature (C)	Humidity Ratio
ASHRAE	A1	15 to 32	20% to 80%	18 to 27	-9°C to 15°C DP and 60% RH
	A2	10 to 35	20% to 80%	18 to 27	-9°C to 15°C DP and 60% RH
	A3	5 to 40	-12°C DP and 8% to 85%	18 to 27	-9°C to 15°C DP and 60% RH
	A4	5 to 45	-12°C DP and 8% to 90%	18 to 27	-9°C to 15°C DP and 60% RH

The inlet ambient temperature for long-term operation under the stated standard must not exceed the 45°C inlet to the card.

## Airflow Direction Support

Passive cards do not include a built-in fan and therefore require forced airflow when the card is powered at all times. The passively cooled Alveo U200 and U250 cards support front-to-back airflow. The following figure illustrates this supported airflow.

Figure 4: Airflow Direction for Passively Cooled Cards



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## Operating Conditions

### Inlet Temperature versus Airflow Requirement in Server

The following tables and figures state the required airflow rate and airflow speed to the card under different operating conditions.

Table 10: Required Flow at Sea Level for an Example 180W Load

Inlet Temperature versus Airflow Requirement PCIe Card Slot (34.8 mm x 106.65 mm) at Sea Level for 85°C Rated QSP		
Inlet Temperature to the Card (°C)	Linear Feet per Minute (LFM)	Cubic Feet per Minute (CFM)
25	426	17
30	426	17
35	476	19
40	526	21
45	601	24
50	701	28



Figure 5: Airflow Condition at Sea Level

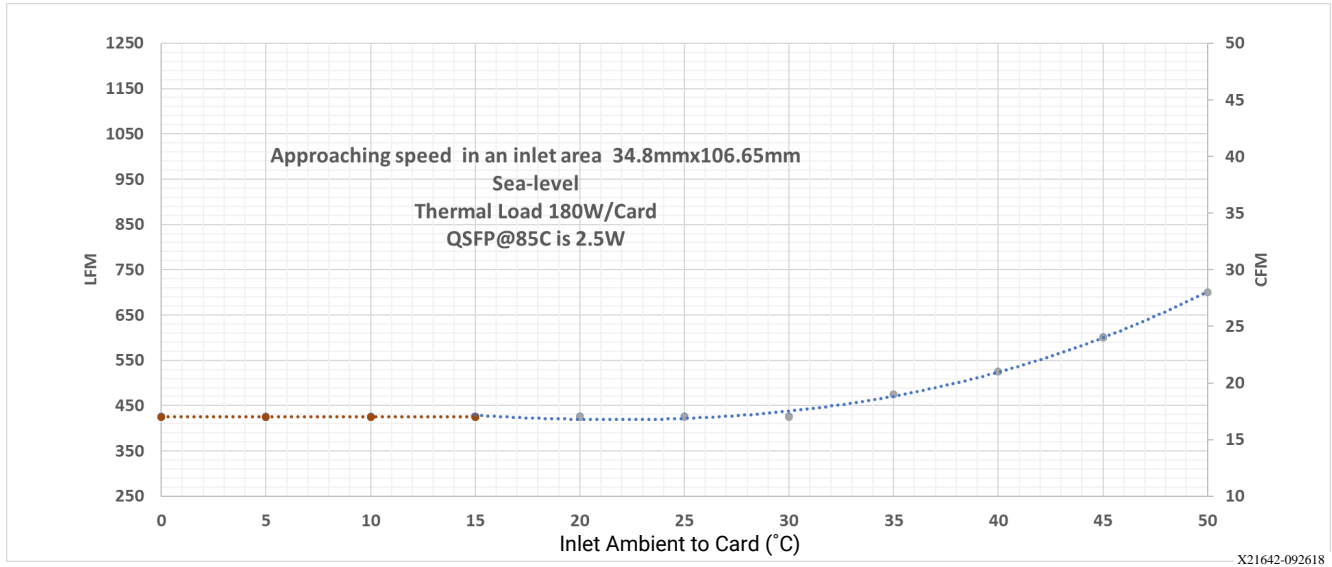
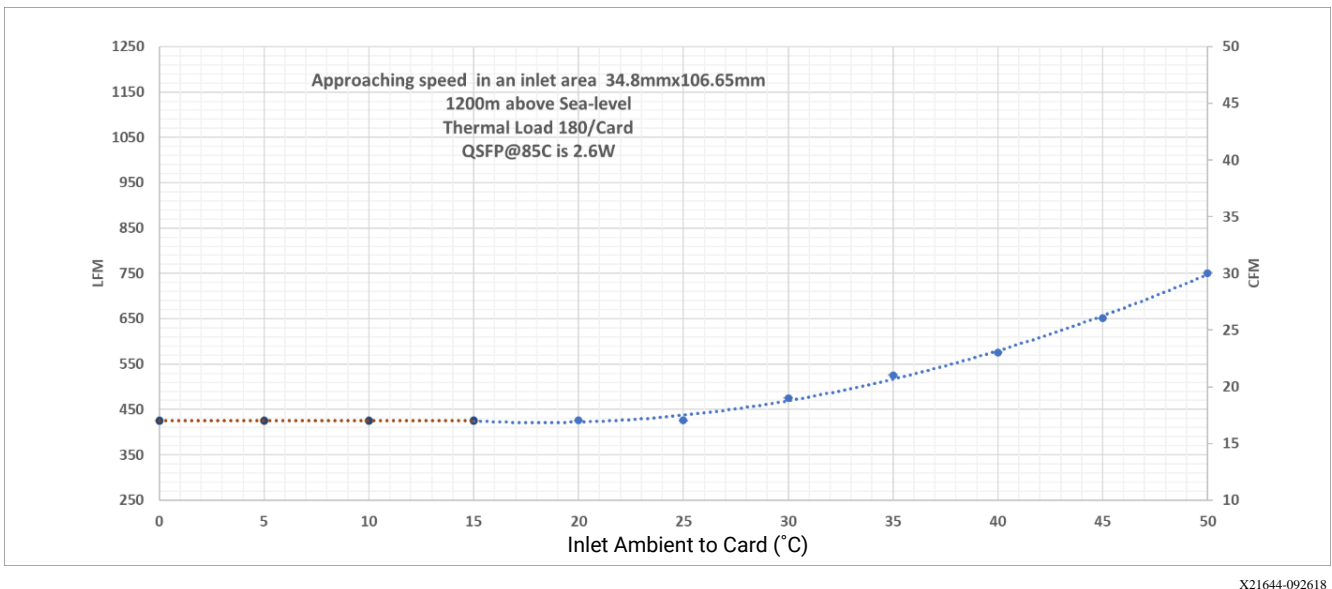


Table 11: Required Flow at 1200m above Sea Level for an Example 180W Load

Inlet Temperature versus Airflow Requirement PCIe Card Slot (34.8 mm x 106.65 mm) at 1200m Level for 85°C Rated QSF		
Inlet Temperature to the Card (°C)	Linear Feet per Minute (LFM)	Cubic Feet per Minute (CFM)
25	426	17
30	476	19
35	526	21
40	576	23
45	651	26
50	751	30

Figure 6: Airflow Condition at 1200m above Sea Level



## Temperature Gradient

The Alveo accelerator card and its thermal management device should be able to operate at a temperature/time gradient of 15°C/hour in its ambient surroundings. The thermal management device is the heat sink, shroud, backplate, top plate, and fan (for active solutions).

## Humidity

The Alveo accelerator card and its thermal management device should be able to operate in a RH (relative humidity) range of 8% to 85% and a dew point of -12°C DP without condensation.

## Storage and Non-Operating Conditions

The Alveo accelerator card and its thermal management device should be stored or maintained in non-operating conditions in a RH range of 5% to 90% without condensation and an ambient temperature range of -40°C to 75°C.

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# Regulatory Compliance Statements

## FCC Class A Products

- U200-A64G
- U200-P64G
- U250-A64G
- U250-P64G

**Note:** These devices are for use with UL Listed Servers or I.T.E.

## Safety Compliance

The following safety standards apply to all products listed above.

- UL 60950-1, 2nd Edition, 2014-10-14 (Information Technology Equipment - Safety - Part 1: General Requirements)
- CSA C22.2 No. 60950-1-07, 2nd Edition, 2014-10-14 (Information Technology Equipment - Safety - Part 1: General Requirements)
- EN 60950-1:2006+A11:2009+A1:2012+A12:2011+A2:2013 (European Union)
- IEC 60950-1:2005 (2nd Edition); Am 1:2009 (International)
- EU LVD Directive 2014/35/EC

## EMC Compliance

The following standards apply.

## Class A Products

- FCC Part 15 – Radiated & Conducted Emissions (USA)
- CAN ICES-3(A)/NMB-3(A) – Radiated & Conducted Emissions (Canada)
- CISPR 32 – Radiated & Conducted Emissions (International)
- EN55032: 2015 – Radiated & Conducted Emissions (European Union)
- EN55024: 2010 +A1:2001+A2:2003 – Immunity (European Union)
- EMC Directive 2014/30/EC
- VCCI (Class A)– Radiated & Conducted Emissions (Japan)
- CNS13438 – Radiated & Conducted Emissions (Taiwan)
- CNS 15663 - RoHS (Taiwan)
- AS/NZS CISPR 32 – Radiated and Conducted Emissions (Australia/New Zealand)
- Article 58-2 of Radio Waves Act, Clause 3 (Korea)

## Regulatory Compliance Markings


When required, these products are provided with the following Product Certification Markings:


- UL Listed Accessories Mark for the USA and Canada
- CE mark
- FCC markings
- VCCI marking
- Australian C-Tick mark
- Korea MSIP mark
- Taiwan BSMI mark


## FCC Class A User Information


The Class A products listed above comply with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

1. This device may not cause harmful interference.
2. This device must accept any interference received, including interference that may cause undesired operation.

 **IMPORTANT!** *This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference, in which case the user will be required to correct the interference at his own expense.*

 **IMPORTANT!** *Cet équipement a été testé et jugé conforme à la Class A digital device, conformément à la règle 15 du standard FCC. Ces limites sont conçues pour fournir des protections contre des interférences nuisibles lorsque l'équipement est utilisé dans un environnement commercial. Cet équipement génère, utilise et peut émettre des énergies de radio-fréquence et, s'il n'est pas installé et utilisé conformément aux instructions, peut nuire aux communications radio. L'exploitation de cet équipement dans une zone résidentielle est susceptible de causer des interférences nuisibles, auquel cas l'utilisateur peut être tenu de prendre des mesures adéquates à ses propres frais.*

 **CAUTION!** *If the device is changed or modified without permission from Xilinx, the user may void his or her authority to operate the equipment.*

 **ATTENTION!** *Si l'appareil est modifié sans l'autorisation de Xilinx, l'utilisateur peut annuler son ability à utiliser l'équipement.*

## Canadian Compliance (Industry Canada)

CAN ICES-3(A)/NMB-3(A)

## VCCI Class A Statement

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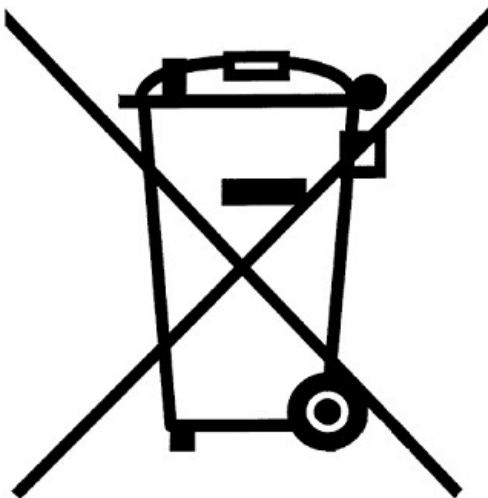
## KCC Notice Class A (Republic of Korea Only)

<p>A급 기기 (업무용 방송통신기기)</p> <p><b>CLASS A device</b> (commercial broadcasting and communication equipment)</p>	<p>이 기기는 업무용(A급)으로 전자파적합등록을 한 기기이오니 판매자 또는 사용자는 이 점을 주의하시기 바라며, 가정외의 지역에서 사용하는 것을 목적으로 합니다.</p> <p>This device has been approved by EMC registration. Distributors or users pay attention to this point. This device is usually aimed to be used in other area except at home</p>
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## BSMI Class A Notice (Taiwan)

<p>警告使用者:</p> <p>此為甲類資訊技術設備，於居住環境中使用時，可能會造成射頻擾動，在此種情況下，使用者會被要求採取某些適當的對策。</p>
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## EU WEEE Logo



## Manufacturer Declaration European Community



## Manufacturer Declaration

Xilinx declares that the equipment described in this document is in conformance with the requirements of the European Council Directive listed below:

- Low Voltage Directive 2014/35/EC
- EMC Directive 2014/30/EC
- RoHS Directive 2011/65/EU

These products follow the provisions of the European Directive 2014/53/EU.

Dette produkt er i overensstemmelse med det europæiske direktiv 1999/5/EC.

Dit product is in navolging van de bepalingen van Europees Directief 1999/5/EC.

Tämä tuote noudattaa EU-direktiivin 1999/5/EC määräyksiä.

Ce produit est conforme aux exigences de la Directive Européenne 1999/5/EC.

Dieses Produkt entspricht den Bestimmungen der Europäischen Richtlinie 1999/5/EC.

Þessi vara stenst reglugerð Evrópska Efnahags Bandalagsins númer 1999/5/EC.

Questo prodotto è conforme alla Direttiva Europea 1999/5/EC.

Dette produktet er i henhold til bestemmelsene i det europeiske direktivet 1999/5/EC.

Este produto cumpre com as normas da Diretiva Europeia 1999/5/EC.

Este producto cumple con las normas del Directivo Europeo 1999/5/EC.

Denna produkt har tillverkats i enlighet med EG-direktiv 1999/5/EC.

This declaration is based upon compliance of the Class A products listed above to the following standards:


EN 55032 (CISPR 32 Class A) RF Emissions Control.

EN 55024:2010 (CISPR 24) Immunity to Electromagnetic Disturbance.


EN 60950-1:2006/A11:2009 A1:2010/A12:2011 Information Technology Equipment- Safety-Part 1: General Requirements.

EN 50581:2012 - Technical documentation for the assessment of electrical and electronic products with respect to the restriction of hazardous substances.

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 **CAUTION!** *In a domestic environment, Class A products may cause radio interference, in which case the user may be required to take adequate measures.*

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 **ATTENTION!** *Dans un environnement domestique, les produits de Classe A peuvent causer des interférences radio, auquel cas l'utilisateur peut être tenu de prendre des mesures adéquates.*

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## Responsible Party

Xilinx, Inc.

2100 Logic Drive, San Jose, CA 95124

United States of America

Phone: (408) 559-7778

## References

The following documents provide additional information.

*Getting Started with Alveo Data Center Accelerator Cards* ([UG1301](#))

## Revision History

The following table shows the revision history for this document.

Section	Revision Summary
10/02/2018 v1.0	
Initial Xilinx release.	N/A

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